

MODULE ENCAPSULATION TECHNOLOGY

SPRINGBORN LABORATORIES

P. Willis

Phase I

IDENTIFY AND DEVELOP LOW COST
MODULE ENCAPSULATION MATERIALS

- POTTANTS
- COVER FILMS
- SUBSTRATES
- ADHESIVES/PRIMERS
- ANTI-SOILING TREATMENTS

Phase II

TASK 1: MATERIALS RELIABILITY

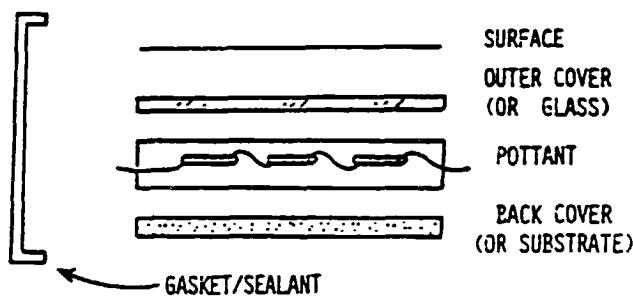
- AGING AND LIFE ASSESSMENT
- ADVANCED STABILIZERS
- ADHESIVE BOND DURABILITY
- HUMIDITY SENSITIVITY
- ELECTRICAL ISOLATION

TASK 2: PROCESS SENSITIVITY

- INTERRELATIONSHIPS OF
 - FORMULATION VARIABLES
 - PROCESS VARIABLES
- IDENTIFY FAILURE MODES
- INDUSTRIAL GUIDANCE

MODULE AND RELIABILITY TECHNOLOGY

Module Components



CURRENT EMPHASIS ON MATERIALS AND MODULE PERFORMANCE CHARACTERISTICS

- DETERMINE CURRENT LEVEL OF PERFORMANCE
- ENHANCE PERFORMANCE (E.G. REFORMULATION)
- SERVICE LIFE PROGNOSIS

PERFORMANCE CRITERIA

- ENVIRONMENTAL DEGRADATION
- MAXIMUM SERVICE TEMPERATURE
- ADHESIVE BOND DURABILITY
- ELECTRICAL INSULATION DURABILITY
- HYDROLYTIC (WATER) STABILITY
- WHAT ARE DOMINANT TYPES OF FAILURE ?
- WHERE IS STABILIZATION NEEDED ?

MODULE AND RELIABILITY TECHNOLOGY

Accelerated Aging Test Program

| CONDITIONS USED INITIALLY | |
|---------------------------|-------------------------|
| <u>METHOD</u> | <u>DEFICIENCIES</u> |
| • THERMAL (AIR OVEN) | • UNNATURAL LIGHT |
| • RS/4 50°C | • NO "WEATHER" |
| • RS/4 WET SPRAY | • NO PREDICTIVE METHODS |
| • RS/4 85°C | • LONG EXPOSURE TIMES |

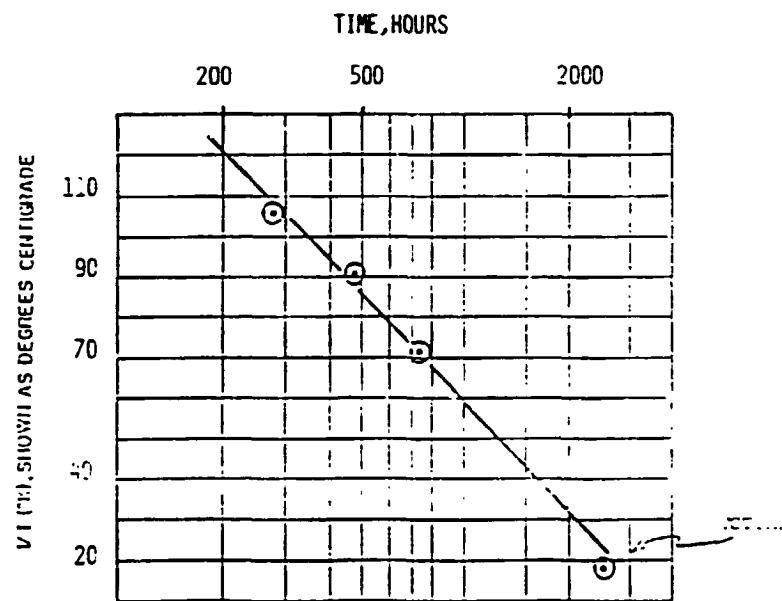
OUTDOOR PHOTOTHERMAL AGING REACTORS (OPTAR)

- USE NATURAL SUNLIGHT, AVOIDS SPECTRAL DISTRIBUTION PROBLEMS WITH ARTIFICIAL LIGHT SOURCES
- USE TEMPERATURE TO ACCELERATE THE PHOTOTHERMAL REACTION
- INCLUDES DARK CYCLE REACTIONS
- INCLUDES DEW / RAIN EXTRACTION
- INTENDED PRIMARILY FOR MODULE EXPOSURE
- EXTRAPOLATE EFFECTS TO LOWER TEMPERATURES

MODULE AND RELIABILITY TECHNOLOGY

Accelerated Aging

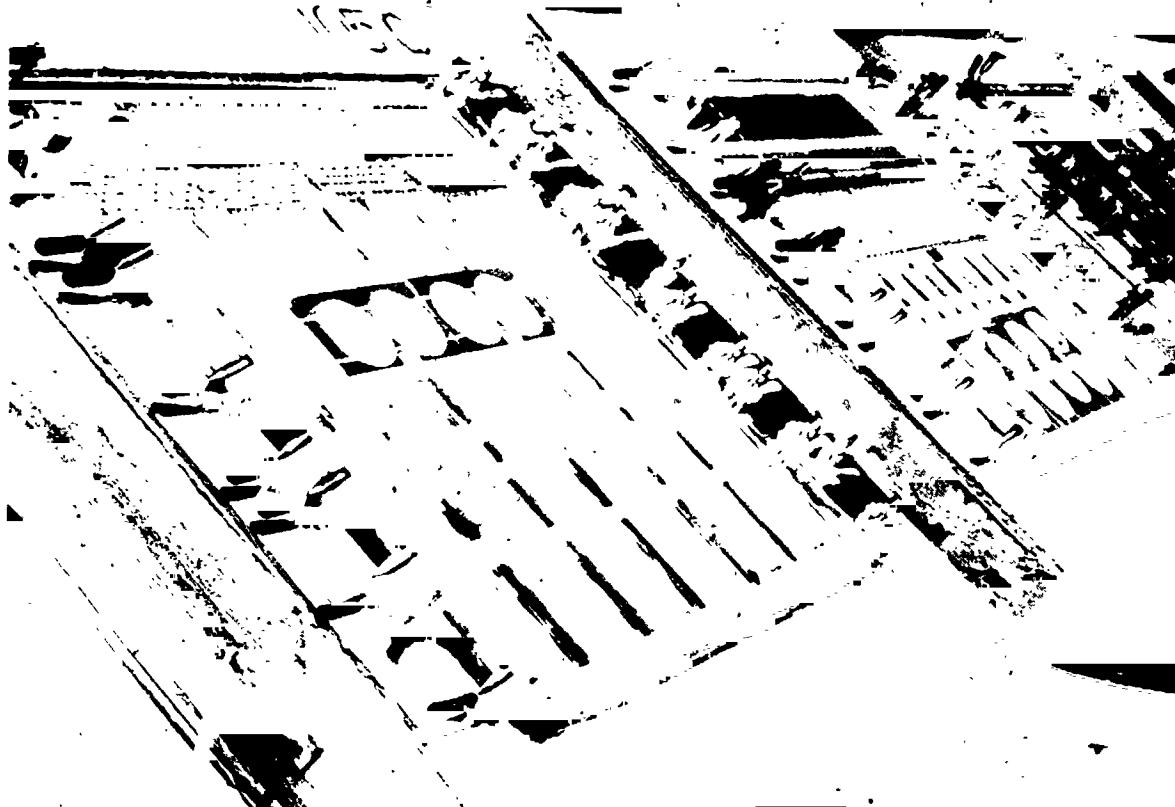
- USEFUL FOR EVALUATING CANDIDATE FORMULATIONS - COMPARISON
- WHOLE MODULES UNDER EXPOSURE
- DETERMINE UPPER LEVEL SERVICE TEMPERATURES
- MODELLING:
 - TIME TO ONSET OF DEGRADATION (INDUCTION PERIOD, t_i)
EXAMPLE: POLYPROPYLENE
 - ARRHENIUS: $\log t_i$ vs. $1/T^\circ$
 - PREDICT SERVICE LIFE BY EXTRAPOLATION TO LOWER TEMPERATURES



MODULE AND RELIABILITY TECHNOLOGY

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Outdoor Photothermal Aging Reactors (OPTAR), Enfield, Connecticut
(70, 90, and 105°C)



MODULE AND RELIABILITY TECHNOLOGY

OPTAR/70°C, 20,000 Hours

- SOME COPPER REACTION W/ EVA 9918
- NO OTHER EFFECTS NOTICEABLE

EVA 9918

EVA 16718

EMA 16717

EVA 14747

STANDARD

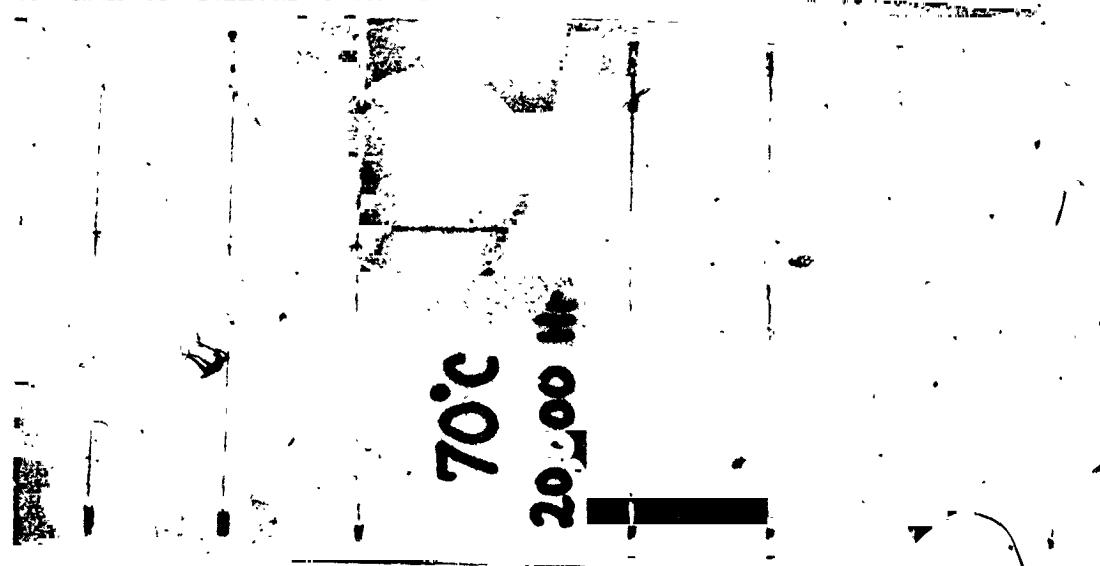
CONTROL

FAST CURE

T8EC UV2098 T170

T8EC UV2098 T170

LOR-101 UV2098 T170



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MODULE AND RELIABILITY TECHNOLOGY

OPTAR/90°C, 20,000 Hours

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- COPPER REACTION IN LUPERSOL-101 RESINS
- OVERALL CONDITION: VERY GOOD

EVA 9918

EVA 16718

EMA 16717

EVA 14747

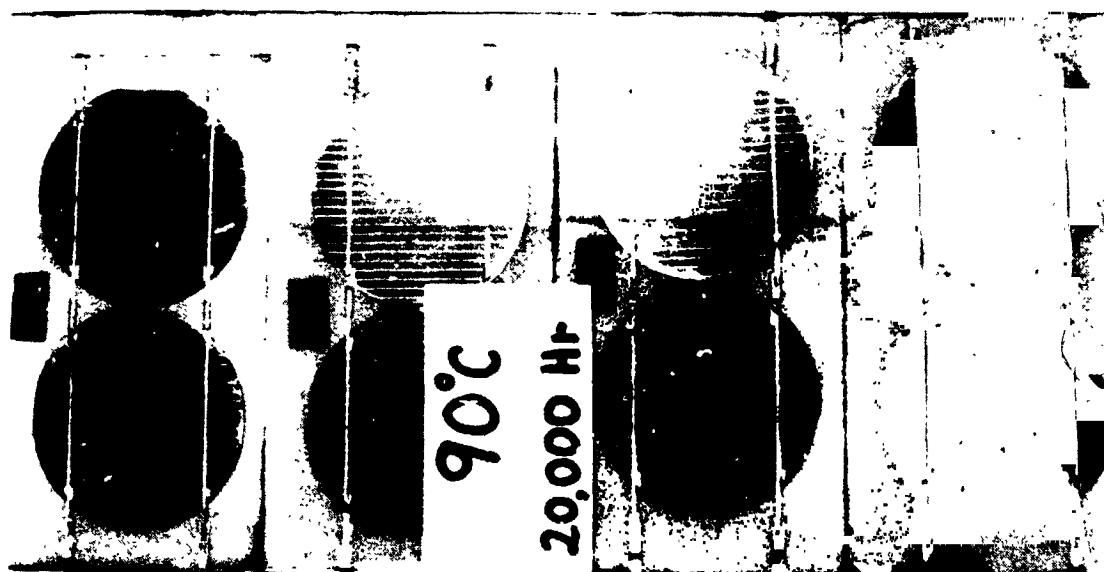
STANDARD
CONTROL

FAST CURE

TBEC UV2098 T770

TBEC UV2098 T770

LUP-101 UV2098 T770



MODULE AND RELIABILITY TECHNOLOGY

OPTAR/105°C, 20,000 Hours

- ALL SHOW SEVERE COPPER REACTION
- BEST PERFORMANCE: EVA-ADVANCED STABILIZER
TBEC, UV-2098, TINUVIN 770

EVA 9918 EVA 16718 EMA 16717 EVA 14747

STANDARD

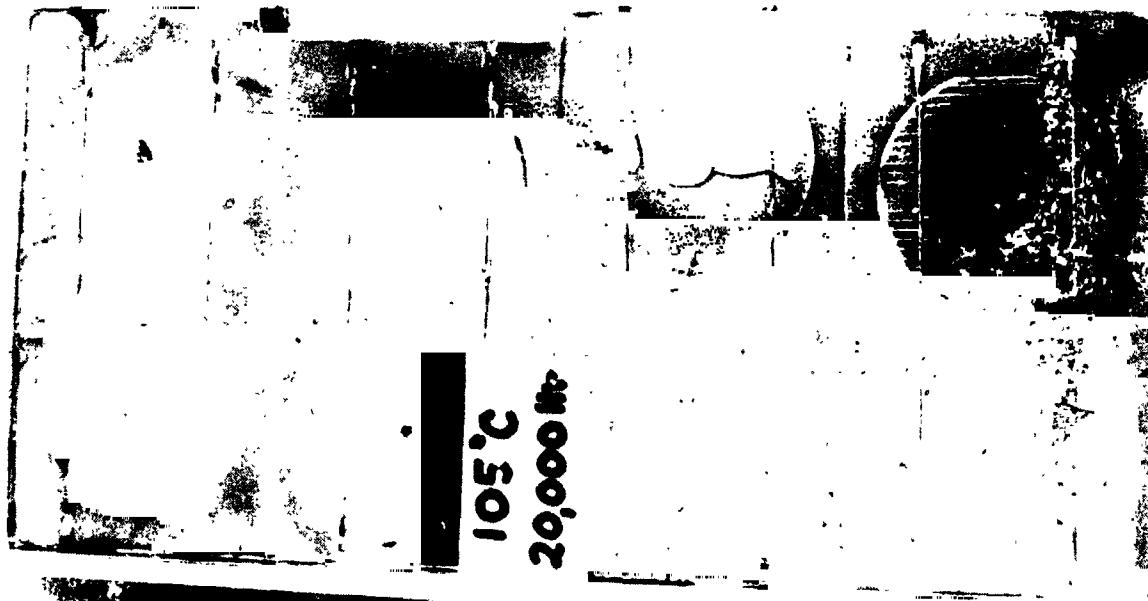
CONTROL

FAST CUR.

TBEC UV2098 T770

TBEC UV2098 T770

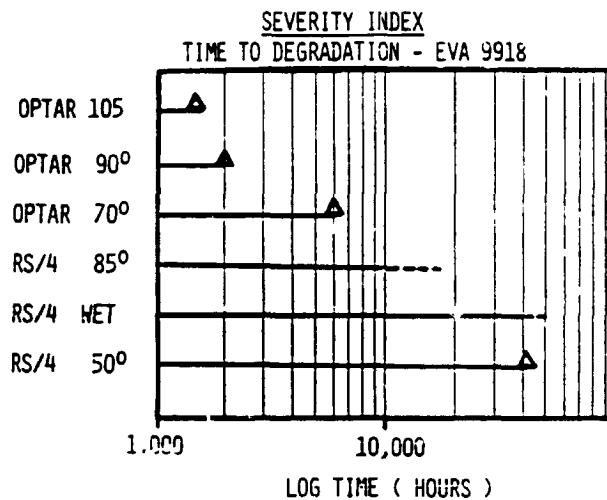
LUP-101 UV2098 T770



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MODULE AND RELIABILITY TECHNOLOGY

Accelerated Aging: Summary of Investigations



- OPTARS MOST EFFICIENT AGING TECHNIQUE
- MODULES HAVE VERY HIGH ENDURANCE
NO EFFECT: 20,000 HRS - 70°C / SUNLIGHT
- DEGRADED MODULES SHOW NO POWER LOSS
- EVA 9918 (STANDARD FORMULA) PERFORMS VERY WELL
- OPTIMIZED EVA FORMULATION:

| | |
|-----------------|--------------|
| LUPERSOL TSEC | CURING AGENT |
| CYASORB UV-2098 | UV SCREENER |
| TINUVIN 770 | STABILIZER |
- RADIOMETER INSTALLED ON OPTAR DEVICES - POSSIBILITY
FOR MODELING BASED ON HEAT PLUS LIGHT ???

MODULE AND RELIABILITY TECHNOLOGY

Adhesion Experiments

STATUS:

- PRIMER FORMULATIONS IDENTIFIED FOR ALMOST ALL INTERFACES IN MODULES
 - POLYMER / METAL
 - POLYMER / INORGANIC
 - POLYMER / ORGANIC
- DR. PLUEDDEMANN - DOW CORNING
- DR. JIM BOERIO - UNIVERSITY OF CINCINNATI
- SELF-PRIMING FORMULATIONS OF EVA (TO GLASS, CELLS) DEVELOPED: AVAILABLE - SPRINGBORN
- NEW PRIMER AVAILABLE - DOW CORNING WITH IMPROVED PROPERTIES - UNDER TEST

Adhesion Diagnostics

- NEW METHOD DEVELOPED
- EVA COMPOUNDED WITH HIGH LOADINGS OF SILANE TREATED GLASS BEADS - RESEMBLES GLASS REINFORCED POLYMER
- EQUILIBRIUM WATER ABSORPTION VALUES MAY PROVIDE NEW METHOD OF EVALUATING ADHESIVE BONDS - INDICATES " DAMAGE " TO BONDS AT THE INTERFACE IS REVERSIBLE UP TO A LIMIT
- DETERMINE DEGRADATION RATES (KINETICS)
- ASSESS SERVICE LIFE
- GENERAL CONCLUSION - BOND DURABILITY - EXCELLENT

MODULE AND RELIABILITY TECHNOLOGY

Electrical Isolation

- POTTONS AND COVER FILMS SERVE AS ELECTRICAL INSULATION
- NEED TO KNOW THICKNESS REQUIRED FOR VOLTAGE STANDOFF
- VARIATION WITH TEMPERATURE, ABSORBED WATER ?
- NEED TO KNOW VARIATION DIELECTRIC STRENGTH WITH AGING: LIGHT, HEAT, HUMIDITY, FIELD STRESS

METHOD:

- HV-DC POWER SUPPLY, SYMMETRIC ELECTRODES
- SPECIFIED RATE OF RISE (500 V/SEC)
- PLOT AVERAGE BREAKDOWN VOLTAGE, V_A VS THICKNESS
- STRAIGHT LINE RELATIONSHIP: SLOPE EQUALS " INTRINSIC DIELECTRIC STRENGTH " (DC)
- MEASUREMENTS TO DATE:
EVA 9918, $DV/DT = 3.48 \text{ kv/MIL}$

RESULTS TO DATE: EVA A9918

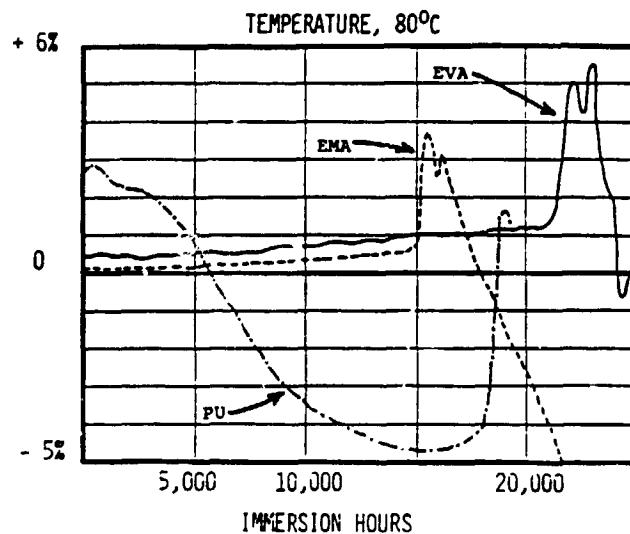
| | | | Δ |
|-------------|----------|--------------------|----------|
| RS/4 (50°C) | 4,000 HR | 3.24 kv/MIL | 93% |
| RS/4 (85°C) | 4,000 HR | 1.98 kv/MIL | 57% |
| RS/4 NET | 4,000 HR | 4.12 kv/MIL | 118% |
| OPTAR 70°C | 2,000 HR | 2.85 kv/MIL | 82% |
| OPTAR 90°C | 2,000 HR | 3.14 kv/MIL | 90% |
| OPTAR 105°C | 2,000 HR | - - UNTESTABLE - - | |

- NEW SPECIMEN GEOMETRY NEEDED - NOW UNDER TEST
- SOME EVIDENCE FOR DECREASE IN DIELECTRIC STRENGTH WITH ACCELERATED AGING
- INCREASE IN STRENGTH WITH WATER EXPOSURE

MODULE AND RELIABILITY TECHNOLOGY

Hydrolytic Stability

- CANDIDATE POTTONS - WATER IMMERSION AT 40°, 60°, 70°, 80° AND 90°
- MEASURE CHANGE IN WEIGHT VERSUS TIME



TIME TO ONSET OF CHANGE, HOURS

| | 70° | 80° | 90° |
|-----|-------|-----------|--------|
| EVA | ? | 21,000 | 14,000 |
| EMA | ? | 15,000 | 9,800 |
| PU | ----- | CONTINUAL | ----- |

- EVA VERY HYDROLYTICALLY STABLE
- DATA WILL BE USED FOR KINETICS

MODULE AND RELIABILITY TECHNOLOGY

Anti-Soiling Treatments

SURFACE CHEMISTRY:

- HARD
- SMOOTH
- HYDROPHOBIC
- OLEOPHOBIC
- ION FREE
- LOW SURFACE ENERGY

SURFACE INVESTIGATED:

- SUNADEX GLASS
- TEDLAR (100 BG 30 UT)
- ACRYLAR (ACRYLIC FILM)

MOST EFFECTIVE TREATMENT:

- E-3820 PERFLUORODECANOIC ACID/SILANE (DOW CORNING)
- STILL EFFECTIVE AT 56 MONTHS OUTDOOR EXPOSURE
- RESULTS IN IMPROVED POWER OUTPUT OF 1% TO 4% - DEPENDING ON SURFACE
- FLUOROALKYL SILANE CHEMISTRY APPEARS TO BE MOST EFFECTIVE

NEW TREATMENTS:

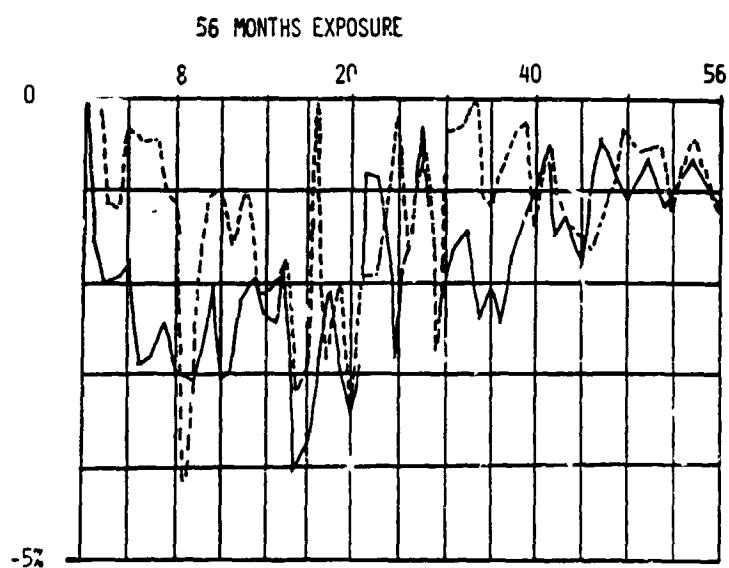
- TWO NEW CANDIDATES FROM DOW CORNING STARTED

MODULE AND RELIABILITY TECHNOLOGY

Soiling Experiments

FIFTY-SIX MONTHS EXPOSURE
ENFIELD, CONNECTICUT

% LOSS IN I_{sc} WITH STANDARD CELL TREATED
SUNDEX GLASS



— CONTROL, NO TREATMENT
- - - E3820
• ESTIMATED AVERAGE POWER IMPROVEMENT,
1%

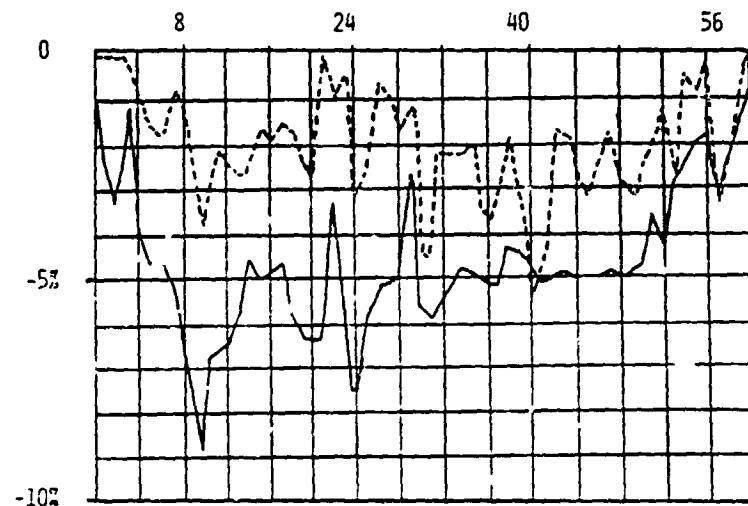
MODULE AND RELIABILITY TECHNOLOGY

Soiling Experiments (Cont'd)

FIFTY-SIX MONTHS EXPOSURE
ENFIELD, CONNECTICUT

* LOSS IN I_{sc} WITH STANDARD CELL TREATED
TEDLAR 10086300UT
(SUPPORT ON GLASS)

56 MONTHS EXPOSURE



— CONTROL, NO TREATMENT
- - - E3820
● ESTIMATED AVERAGE POWER IMPROVEMENT, 3.8%

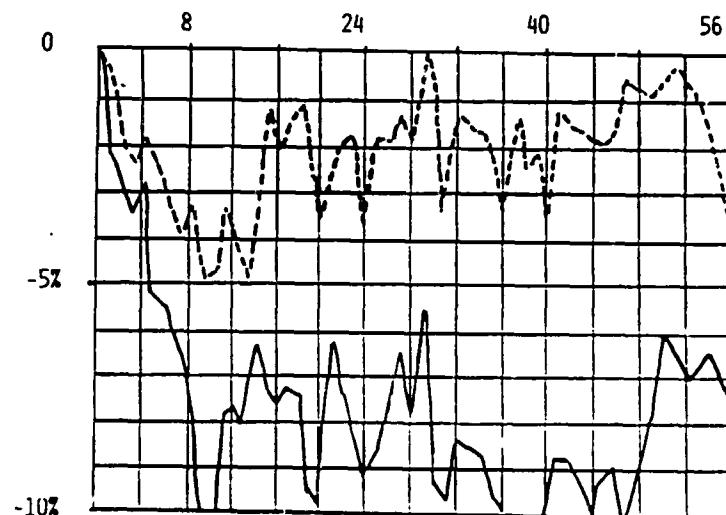
MODULE AND RELIABILITY TECHNOLOGY

Soiling Experiments (Cont'd)

FIFTY-SIX MONTHS EXPOSURE
ENFIELD, CONNECTICUT

% LOSS IN I_{sc} WITH STANDARD CELL TREATED ACRYLAR
(SUPPORTED ON GLASS)

56 MONTHS EXPOSURE



- CONTROL, NO TREATMENT
- - - OZONE + E3820
- ESTIMATED AVERAGE POWER IMPROVEMENT,
3.9%

MODULE AND RELIABILITY TECHNOLOGY

Process Sensitivity

GOALS:

- UNDERSTAND RELATIONSHIPS BETWEEN ALL MANUFACTURING VARIABLES
- DEFINE FAILURE / ACCEPTABILITY CRITERIA
- STATISTICAL ANALYSIS OF RESULTS
- DEFINE OPTIMUM CONDITIONS
- PREDICT MANUFACTURING YIELD
- PROVIDE DOCUMENTATION TO INDUSTRY

VARIABLES

FORMULATION:

- POTENT COMPOSITION
- CURING AGENTS
- PRIMERS
- STORAGE CONDITIONS

PROCESSING:

- VACUUM PRESSURE
- TEMPERATURE, ULTIMATE, °C
- TEMPERATURE, RATE OF RISE, °C / MIN.
- DWELL TIMES
- RATE OF COOLING

MODULE AND RELIABILITY TECHNOLOGY

Testing and Performance Criteria

- METHOD:
- PREPARE TEST MODULES AND / OR OTHER TEST SPECIMENS WITH CHANGE IN SIGNIFICANT VARIABLE(S)
 - DEVELOPED STANDARD TEST SPECIMEN
 - DEVELOPED STANDARD TEST PROTOCOL
 - COLLECTED UNIFORM DATA SETS
 - QUANTITATE THE EFFECTS

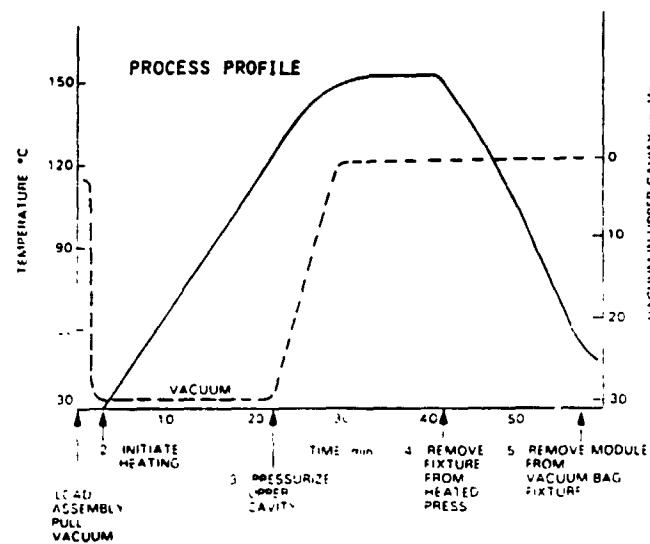
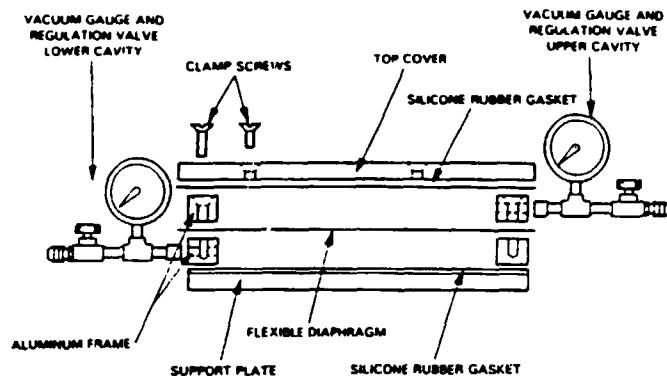
| <u>COMPONENT</u> | <u>CRITERION</u> | <u>TEST</u> |
|---------------------|--|--|
| POTTANT | ADEQUATE CURE | PERCENT GEL THERMAL CREEP |
| | TRAPPED BUBBLES DISCOLORATION | VISUAL VISUAL |
| CELLS | BREAKAGE INTERCONNECT REGISTRATION | VISUAL, RESISTANCE RESISTANCE VISUAL |
| COVER FILMS | TEARS / PUNCTURES WARPING / SHRINKAGE | VISUAL VISUAL |
| GLASS (SUPERSTRATE) | FRACTURE | VISUAL |
| ADHESION | BOND STRENGTH ENDURANCE | PEEL TEST WATER SOAK (50°C) |

MODULE AND RELIABILITY TECHNOLOGY

Process Equipment

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EXPERIMENTAL LAMINATOR



- MICROPROCESSOR CONTROLLED EXPERIMENTAL LAMINATOR CONSTRUCTED
- STUDIES STARTED ON PROCESSING PROFILES
 - RATE OF HEATING (HOW SLOW, HOW FAST ?)
 - VACUUM TIMING
 - RATE OF COOLING

MODULE AND RELIABILITY TECHNOLOGY

Process Sensitivity: Observations and Recommendations

FORMULATION VARIABLES

- EVA FORMULATIONS RELATIVELY INSENSITIVE TO QUANTITY OF PEROXIDE BUT VERY SENSITIVE TO AIR EXPOSURE - EVAPORATION
- EVA WITH LUPERSOL - TBEC MUCH LESS SENSITIVE
- UNWRAP / CUT EVA JUST BEFORE MODULE MANUFACTURING - LIMIT AIR EXPOSURE
- SELF-PRIMING GRADE WORKS WELL

PROCESS VARIABLES

- UPPER AND LOWER LIMITS DETERMINED:
 - ULTIMATE TEMPERATURE
 - RATE OF RISE - TEMPERATURE
 - BACKPRESSURE TIMING
- DOMINANT FAILURE : ADHESION (POTTANT / GLASS)
 - BOUNDS THE NARROWEST PROCESSING " WINDOW "
- EVA WITH LUPERSOL-TBEC HAS WIDER WINDOW THAN EVA 3918
 - STORAGE : MORE STABLE TO EXPOSURE
 - PROCESSING : WIDEP RANGE OF CONDITIONS
- INDUSTRIAL " TROUBLE SHOOTING GUIDE " PREPARED

MODULE AND RELIABILITY TECHNOLOGY

Thin-Film Encapsulation

(AMORPHOUS PHOTOVOLTAICS)

TYPES:

- SUPERSTRATE - ON GLASS
- SUBSTRATE - ON STAINLESS STEEL

FAILURE MECHANISMS:

CORROSION, BREAKAGE (GLASS), ABRASION,
ELECTRICAL SHORTING, OTHERS ? ? ?

Encapsulation Requirements (Anticipated)

| <u>COMPONENT</u> | <u>PROPERTY</u> |
|------------------|--|
| OUTER COVER | <ul style="list-style-type: none">● INHERENTLY WEATHERABLE● ABRASION / CUT RESISTANT |
| BACK COVER | <ul style="list-style-type: none">● WHITE (EMISSIVE)● WEATHER RESISTANT |
| POTTANT | <ul style="list-style-type: none">● PROCESSABLE <100°C● CURABLE - CREEP RESISTANT● LOW WATER ABSORPTION● HIGH OPTICAL TRANSMISSION |
| DURABLE BONDING | <ul style="list-style-type: none">● ALI. INTERFACES● LONG SERVICE LIFE● LOW COST |

Manufacture/Process

- FAST
- AUTOMATABLE
- INEXPENSIVE

MODULE AND RELIABILITY TECHNOLOGY

Thin-Film Encapsulation: Candidate Materials and Processes

BACK COVERS

- WHITE TELAR
- FLUOROPOLYMERS BEST CHOICE
- FEP CURRENTLY FAVORED DUE TO HIGH TRANSPARENCY AND OUTSTANDING WEATHERABILITY

| <u>FILM</u> | <u>REF. INDEX</u> | <u>% T</u> | <u>COST</u> <u>\$/FT²/MIL</u> |
|-------------|-------------------|------------|---|
| FEP | 1.34 | 93.6 | 0.10 |

POTTANTS: CONDUCTING INVESTIGATIONS

| <u>MATERIAL CLASS</u> | <u>MANUFACTURER</u> | <u>\$/LB</u> |
|--|---------------------|--------------|
| ETHYLENE/VINYL ACETATE | DU PONT, USI | .60 - .80 |
| ETHYLENE/ACRYLIC | DCW, GULF | .80 - 1.00 |
| IONOMER | DU PONT | 1.08 - 1.60 |
| ALIPHATIC URETHANE | UPJOHN | .30 - 2.50 |
| HOT MELT ADHESIVES (HYDROCARBON, POLYAMIDE POLYETHER, ACRYLIC) | MANY | .80 - 2.50 |

CURE METHOD:

- MOISTURE CURE (MODIFIED CHEMISTRY)
- PEROXIDE DECOMPOSITION (HEAT)
- UV CURE (PHOTOINITIATION)
- MOISTURE CURABLE SELF - PRIMING POTTANT UNDER DEVELOPMENT. SILANE / ACRYLIC CHEMISTRY

ENCAPSULATION METHOD:

- FILM LAMINATION: EXTRUDE THE POTTANT ON AN OUTER COVER FILM AS A CARRIER, USE COMBINATION FOR LAMINATION.

MODULE AND RELIABILITY TECHNOLOGY

Conclusions

ACCELERATED AGING:

- "OPTAR" METHOD BEST AGING TECHNIQUE DISCOVERED SO FAR
- MODELING / LIFE PREDICTION ENCOURAGING
 - 70° & 90°C VERY GOOD CONDITION
 - COPPER REACTIONS NOT AS SEVERE AS ANTICIPATED - EXCEPT AT 105°C
 - LUPERSOL - TBEC CURED FORMULATIONS APPEAR MORE STABLE
 - BEST STABILIZERS : UV-2098 SCREENER, TINUVIN 770 (BOTH CYANAMIDE)
 - MODULE PERFORMANCE - EXCELLENT (OPTAR 90°C - 20,000 HR - NO CHANGE)

ADHESION:

- NEW TEST METHOD FOR PRIMER EVALUATION AND BOND DURABILITY
- CAN DEMONSTRATE BOND RECOVERY & LIMIT OF REVERSIBILITY
- SELF-PRIMING EVA WORKS WELL

ELECTRICAL ISOLATION:

- INTRINSIC DIELECTRIC TEST METHOD DEVELOPED
- SOME EVIDENCE OF DECREASE IN DIELECTRIC STRENGTH WITH ACCELERATED AGING

MODULE AND RELIABILITY TECHNOLOGY

Conclusions (Cont'd)

HYDROLYTIC STABILITY:

- EVA APPEARS EXCELLENT

PROCESS SENSITIVITY:

- DOMINANT PROCESS FAILURE MODE : ADHESION
- EVA STORAGE ESSENTIAL
- LUPERSOL TBEC FORMULATIONS - WIDER PROCESS LATITUDE, BETTER STORAGE STABILITY

SOILING:

- TREATMENTS STILL EFFECTIVE AFTER 56 MONTHS

THIN-FILM PV:

- CANDIDATES BEING SELECTED / DEVELOPED